

IN THE SPECIFICATION:

Please amend the specification as follows:

Page 3, second full paragraph:

Thus, as shown in FIG. 27, the surface acoustic wave resonator 116 is cascaded between the terminal 102 and the surface acoustic wave filter 101. The surface acoustic wave resonator 116 has an IDT electrode 117 and reflector electrodes ~~116 and 118~~ and 119. The IDT electrode 117 is formed with a plurality of electrode fingers. An upper bus-bar side of the IDT electrode 117 is connected to the terminal 102. A lower bus bar side of the IDT electrode 117 is connected to an upper bus-bar side of the IDT electrode 103 of the surface acoustic wave filter 101.

Page 17, second through fifth paragraphs:

FIG. 21 is a plan sectional view showing a configuration of an antenna duplexer according to Embodiment ~~6~~ 5 of the present invention;

FIG. 22(a) is a schematic sectional view showing a configuration of an antenna duplexer according to Embodiment ~~6~~ 5 of the present invention;

FIG. 22(b) is a schematic sectional view showing the configuration of the antenna duplexer according to Embodiment ~~6~~ 5 of the present invention;

FIG. 22(c) is a schematic sectional view showing the configuration of the antenna duplexer according to Embodiment ~~6~~ 5 of the present invention;

Page 29, first full paragraph:

Further, in Embodiments 1 and 2, described above, the connection points 300, 310, ~~and 320 and connection points~~ 320, 330 and other connection points are examples of connection portions of the present invention. However, the connection portion according to the present invention may be an arbitrary part of an electric path connecting the surface acoustic wave resonators together, the surface acoustic wave resonator and the longitudinal coupled mode type surface acoustic wave filter together,

or the terminal 102 and the surface acoustic wave resonator together. Thus, the connection portion is not limited by the specific position or size of the actual connection point.

Page 39, third full paragraph:

The receiving piezoelectric substrate 42 is packaged in the package 53. The receiving surface acoustic wave filter 101 is installed on the piezoelectric substrate 42. The external electrodes 51 of the package ~~52~~ 53 and the terminal 109 are connected to the respective connection points via the corresponding external electrodes 51.